

Title (en)

CONTACT DEVICE FOR ESTABLISHING AN ELECTRICAL CONNECTION TO A CONTACT POINT OF A PRINTED CIRCUIT BOARD

Title (de)

KONTAKTEINRICHTUNG ZUM HERSTELLEN EINER ELEKTRISCHEN VERBINDUNG MIT EINER KONTAKTSTELLE EINER LEITERPLATTE

Title (fr)

DISPOSITIF DE CONTACT POUR LA RÉALISATION D'UNE CONNEXION ÉLECTRIQUE AVEC LE SITE DE CONTACT D'UN CIRCUIT IMPRIMÉ

Publication

EP 3022805 A1 20160525 (DE)

Application

EP 14736386 A 20140704

Priority

- DE 102013107508 A 20130716
- EP 2014064305 W 20140704

Abstract (en)

[origin: WO2015007545A1] A contact device for establishing an electrical connection to a contact point of a printed circuit board can be inserted into a contact hole in the printed circuit board, said contact hole being arranged at the contact point. In this case, provision is made for the contact device (2) to have a contact element (20) comprising a deformation section (201) and to have a screw element (22) which is to be screwed into the contact element (20), wherein the deformation section (201) is in a longitudinal extension state in a pre-fitted state and is deformed out of the longitudinal extension state by the screw element (22), which is at least partially screwed into the contact element (20), in a fitted state. A printed circuit board arrangement comprising a contact device is provided in this way, said printed circuit board arrangement allowing simple connection of the contact device with a fixed, contact-making connection in a fitted state.

IPC 8 full level

F16B 37/06 (2006.01); **H01R 4/06** (2006.01); **H01R 4/36** (2006.01); **H01R 12/51** (2011.01); **H01R 12/53** (2011.01); **H01R 12/58** (2011.01); **H05K 3/32** (2006.01)

CPC (source: EP US)

H01R 12/58 (2013.01 - EP US); **H01R 12/585** (2013.01 - US); **H01R 43/205** (2013.01 - US); **H05K 3/325** (2013.01 - EP US); **F16B 37/067** (2013.01 - EP US); **H01R 4/06** (2013.01 - EP US); **H01R 4/36** (2013.01 - EP US); **H01R 12/515** (2013.01 - EP US); **H01R 12/53** (2013.01 - EP US); **H05K 2201/1031** (2013.01 - EP US); **H05K 2201/10409** (2013.01 - EP US); **Y02P 70/50** (2015.11 - EP US)

Citation (search report)

See references of WO 2015007545A1

Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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